Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)

Contact Info: ti.com/support

Form/Declaration Type: Distribute - RoHS and IEC 62474 DB

Created on: 06/09/2022

Details for "TLV70015DCKR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV70015DCKR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DCK 5	1.25x2x0.9	7.9

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire			·				
Not Categorized	Proprietary Materials		0.000001	0.003349	33	0.000013	0
Precious Metals	Gold	7440-57-5	0.029855	99.996651	999967	0.379491	3795
Sub-Total			0.029856	100	1000000	0.379504	3795
Die Attach Adhesive							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.011773	29.998726	299987	0.149648	1496
Other Inorganic Materials	Silica	7631-86-9	0.001766	4.499936	44999	0.022448	224
Other Organic Materials	Chlorine	7782-50-5	0.000014	0.035673	357	0.000178	2
Thermoplastics	Ероху	85954-11-6	0.025692	65.465664	654657	0.326575	3266
Sub-Total			0.039245	100	1000000	0.498849	4988
Lead Frame	•	•					
Copper and Its Alloys	Copper	7440-50-8	3.241136	97.04	970400	41.198533	411985
Copper and Its Alloys	Iron	7439-89-6	0.08684	2.6	26000	1.103835	11038
Copper and Its Alloys	Phosphorus	7723-14-0	0.00501	0.15	1500	0.063683	637
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000334	0.01	100	0.004246	42
Zinc and Its Alloys	Zinc	7440-66-6	0.00668	0.2	2000	0.08491	849
Sub-Total			3.34	100	1000000	42.455208	424552
Lead Frame Plating	•	•					
Nickel and Its Alloys	Nickel	7440-02-0	0.057072	95.12	951200	0.72545	7255
Precious Metals	Gold	7440-57-5	0.000468	0.78	7800	0.005949	59
Precious Metals	Palladium	7440-05-3	0.00246	4.1	41000	0.031269	313
Sub-Total			0.06	100	1000000	0.762668	7627
Mold Compound		<u> </u>					
Other Inorganic Materials	Fused Silica	60676-86-0	3.535038	84.999984	850000	44.934363	449344
Other Plastics and Rubber	Carbon Black	1333-86-4	0.012477	0.300009	3000	0.158597	1586
Thermoplastics	Ероху	85954-11-6	0.611354	14.700006	147000	7.771006	77710
Sub-Total			4.158869	100	1000000	52.863966	528640
Semiconductor Device	•	•			-		
Ceramics / Glass	Doped Silicon	7440-21-3	0.239145	100	1000000	3.039806	30398
Sub-Total			0.239145	100	1000000	3.039806	30398
Total			7.867115			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/09/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.